

200W LOW CAPACITANCE UNBUMPED FLIP CHIP TVS ARRAY

DESCRIPTION

The ULC0402FCxxC Series Flip Chips employ advanced silicon P/N junction technology for unmatched board-level transient voltage protection against Electrostatic Discharge (ESD) and Electrical Fast Transients (EFT). Developed specifically for high-density circuit protection, this series meets the IEC 61000-4-2 and 61000-4-4 requirements. These devices are ideally suited for handheld devices, PCMCIA and SMART cards.

This low capacitance series provides ESD protection greater than 25 kilovolts with a peak pulse power dissipation of 200 Watts per line for an 8/20µs waveform. In addition, the ULC0402FCxxC series features superior clamping performance, low leakage current characteristics and a response time of less than a nanosecond. Their low inductance virtually eliminates overshoot voltage due to package inductance.

FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air 15kV, Contact 8kV
- Compatible with IEC 61000-4-4 (EFT): 40A, 5/50ns
- ESD Protection > 25 kilovolts
- Available in Voltages Ranging from 3.3V to 36V
- 200 Watts Peak Pulse Power per Line (tp = 8/20μs)
- Bidirectional and Monolithic Structure
- Low Clamping Voltage
- Low Capacitance
- Protection for 1 Line
- RoHS Compliant
- REACH Compliant

MECHANICAL CHARACTERISTICS

- Standard EIA Chip Size: 0402
- Approximate Weight: 0.73 milligrams
- Lead-Free Plating
- Flammability Rating UL 94V-0
- 8mm Plastic Tape per EIA Standard 481

APPLICATIONS

- SMART Phones
- Portable Electronics
- SMART Cards

PIN CONFIGURATION



TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified							
PARAMETER SYMBOL VALUE UNITS							
Peak Pulse Power (tp = 8/20µs) - See Figure 1	P _{pp}	200	Watts				
Operating Temperature	T _A	-55 to 150	°C				
Storage Temperature	Т _{stg}	-55 to 150	°C				

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified								
PART NUMBER (Note 1)	RATED STAND-OFF VOLTAGE V WM VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ I _p = 1A V _c VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ 8/20µS V _c @ I _{PP}	MAXIMUM LEAKAGE CURRENT (Note 2) @V _{WM} Ι _D μΑ	TYPICAL CAPACITANCE @0V, 1MHz C pF		
ULC0402FC3.3C	3.3	4.0	7.0	12.5V @ 16A	75*	70		
ULC0402FC05C	5.9	6.0	11.0	13.0V @ 15A	10**	35		
ULC0402FC08C	8.0	8.5	13.2	18.0V @ 11A	1	32		
ULC0402FC12C	12.0	13.3	19.8	26.9V @ 7.4A	1	30		
ULC0402FC15C	15.0	16.7	25.4	34.5V @ 5.8A	1	25		
ULC0402FC24C	24.0	26.7	37.2	50.6V @ 4A	1	20		
ULC0402FC36C	36.0	40.0	70.0	80.0V @ 2.5A	1	18		

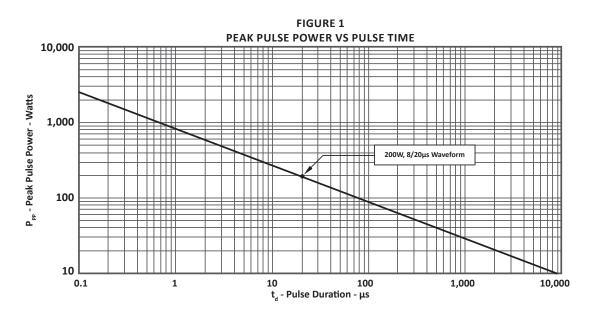
NOTES

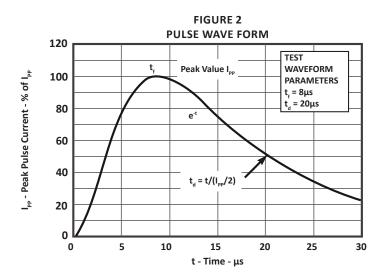
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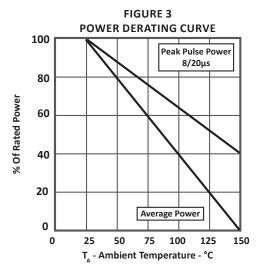
All devices are bidirectional. Electrical characteristics apply in both directions.
 *Maximum leakage current < 5µA @ 2.8V. **Maximum leakage current < 500nA @ 3.3V.

TYPICAL DEVICE CHARACTERISTICS

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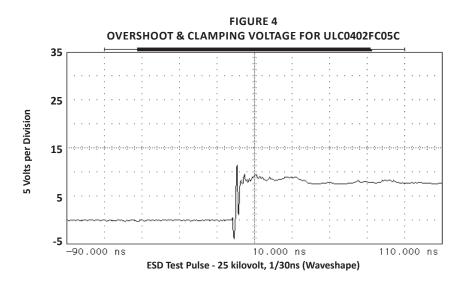
TYPICAL DEVICE CHARACTERISTICS

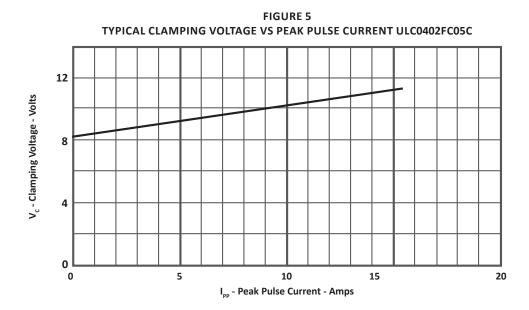
PROJEK DEV

CES

Only One Name Means ProTek'Tion™

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SOLDER REFLOW INFORMATION

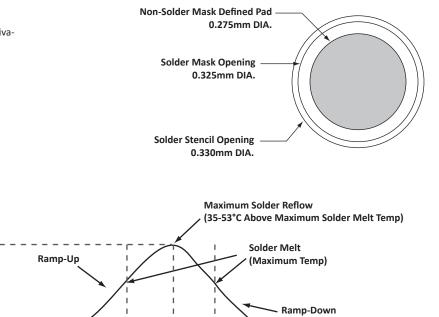
PRINTED CIRCUIT BOARD RECOMMENDATIONS							
PARAMETER VALUE							
Pad Size on PCB	0.275mm						
Pad Shape	Round						
Pad Definition	Non-Solder Mask Defined Pads						
Solder Mask Opening	0.325mm Round						
Solder Stencil Thickness	0.150mm						
Solder Stencil Aperture Opening (Laser cut, 5% tapered walls)	0.330mm Round						
Solder Paste Type	No Clean						
Pad Protective Finish	OSP (Entek Cu Plus 106A)						
Tolerance - Edge To Corner Ball	±50μm						
Solder Ball Side Coplanarity (Only applies to bumped devices)	±20μm						
Maximum Dwell Time Above Liquidous (183°C)	60 seconds						
Soldering Maximum Temperature	270°C						

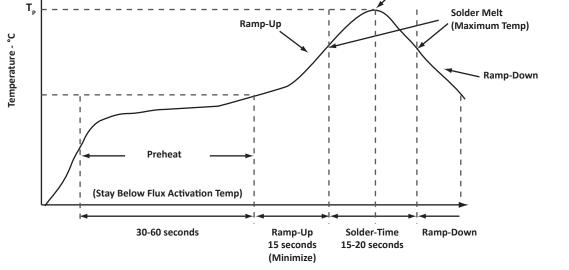
REQUIREMENTS

Temperature:

 $T_{\rm p}$ for Lead-Free (Sn/Ag/Cu): 260-270°C Preheat time and temperature depends on solder paste and flux activation temperature, component size, weight, surface area and plating.

RECOMMENDED NON-SOLDER MASK DEFINED PAD ILLUSTRATION





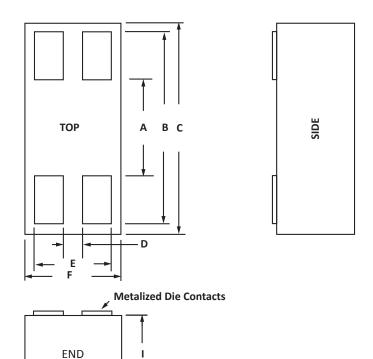
U0402 PACKAGE INFORMATION

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OUTLINE DIMENSIONS							
DIM	MILLIN	IETERS	INC	HES			
DIM	MIN	MAX	MIN	MAX			
А	0.	61	0.0)24			
В	0.3	86	0.034				
С	0.98	1.02	0.038 0.040				
D	0.	10	0.0	004			
E	0.3	35	0.0)14			
F	0.458	0.508	0.018	0.020			
I	I 0.406 0.016						
NOTES							

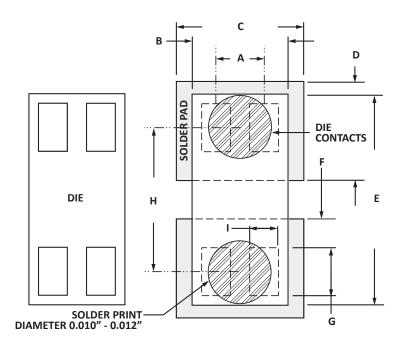
1. Controlling dimensions in inches.

2. Decimal tolerance: .xxx ± 0.05mm (0.002").
 3. Maximum chip size: 1.02mm (0.040") by 0.51mm (0.020").



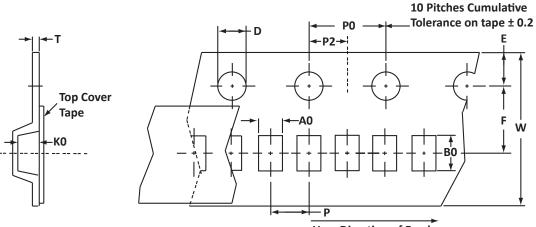
LAYOUT DIMENSIONS						
DIM	MILLIMETERS	INCHES				
DIM	NOMINAL	NOMINAL				
А	0.23	0.009				
В	0.48	0.019				
С	0.69	0.027				
D	0.46	0.018				
E	0.99	0.039				
F	0.20	0.008				
G	0.20	0.008				
Н	0.66	0.026				
Ι	0.13	0.005				
NOTES 1. Controlling dimensions in inches.						

2. Decimal tolerance: .xxx ± 0.05mm (0.002").



TAPE AND REEL INFORMATION

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User Direction of Feed

SPECIFICATIONS											
REEL DIA. TAPE WIDTH	A0	В0	ко	D	E	F	w	PO	P2	Р	Tmax
178(7") 8 (0.70 ± 0.05	1.15 ± 0.10	0.56 ± 0.05	1.55 ± 0.05	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	0.25
178(7") 8 0.70 ± 0.05 1.15 ± 0.10 0.56 ± 0.05 1.75 ± 0.10 3.50 ± 0.05 8.00 ± 0.20 4.00 ± 0.05 2.00 ± 0.05 0.25 NOTES 1. Dimensions in millimeters. 2. Top view of tape. Metal contacts are face down in tape package. 3. Orientation: preferred stencil - 0.1mm (0.004"). 4.00 ± 0.05 5.000 (pocket under hole skipped) or 10,000 pieces per reel. Image: Colspan="4">Image: Colspan="4">Colspan="4">Image: Colspan="4">Image: Colspan="4" Image: Colspan="4">Image: Colspan="4" <t< td=""></t<>											

ORDERING INFORMATION								
BASE PART NUMBER (xx = Voltage)	I LEADEREE SUFFIX I TAPE SUFFIX I OTY/REFI I REFI SIZE I TUBE OT							
ULC0402FCxxC	-LF	-T75-1	5,000	7″	n/a			
ULC0402FCxxC	-LF	-T710-1	10,000	7"	n/a			

COMPANY INFORMATION

COMPANY PROFILE

ProTek Devices, based in Tempe, Arizona USA, is a manufacturer of Transient Voltage Suppression (TVS) products designed specifically for the protection of electronic systems from the effects of lightning, Electrostatic Discharge (ESD), Nuclear Electromagnetic Pulse (NEMP), inductive switching and EMI/RFI. With over 25 years of engineering and manufacturing experience, ProTek designs TVS devices that provide application specific protection solutions for all electronic equipment/systems.

ProTek Devices Analog Products Division, also manufactures analog interface, control, RF and power management products.

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PATENT INFORMATION: This device is patented under U.S. Patent No. Des. "D456,367S".